



# SILFILL CONDUCTIVE ADHESIVE

## AS Shielding

### Further Specifications:

#### SILVER LOADED EPOXY ADHESIVE: PPT Bond Epoxy SE-2P

##### UNCURED PROPERTIES

Colour	Silver
Form	Semi viscous paste
Cure time at 23oC / 50% RH	24 Hours
Recommended minimum time before stressing bond	48 Hours

##### CURED PROPERTIES

Density	3.0g/cm <sup>3</sup>
Adhesion – lap shear (aluminium to aluminium)	850 N.cm <sup>2</sup>
Service temperature range	-50oC to 200oC
Bond resistance (aluminium to aluminium)	<10mΩ/cm <sup>2</sup>
Thermal conductivity	4.8 Wm/K
Recommended bond thickness	0.25mm

#### NICKEL GRAPHITE LOADED RTV SILICONE: PPT Bond AS-N

##### UNCURED PROPERTIES

Colour	Grey
Form	Semi flowable paste
Cure time at 23oC / 50% RH	24 Hours
Recommended minimum time before stressing bond	48 Hours

##### CURED PROPERTIES

Density	2.1g/cm <sup>3</sup>
Hardness	75 Shore A
Adhesion – lap shear (aluminium to aluminium)	150 N.cm <sup>2</sup>
Service temperature range	-50oC to 150oC
Bond resistance (aluminium to aluminium)	<10mΩ/cm <sup>2</sup>
Thermal conductivity	1.0 Wm/K
Recommended bond thickness	0.05 - 05mm

#### SILVER ALUMINIUM LOADED RT SILICONE: PPT Bond AS-J

##### UNCURED PROPERTIES

Colour	Light tan
Form	Semi flowable paste
Cure time at 23oC / 50% RH	24 Hours
Recommended minimum time before stressing bond	48 Hours

##### CURED PROPERTIES

Density	2.1g/cm <sup>3</sup>
Hardness	65 Shore A
Adhesion – lap shear (aluminium to aluminium)	150 N.cm <sup>2</sup>
Compression recommended (allowed range) 25%	(10 - 50%)
Service temperature range	-50oC to 125oC
Bond resistance (aluminium to aluminium)	<20mΩ/cm <sup>2</sup>
Thermal conductivity	0.8 Wm/K
Recommended bond thickness	0.05 - 05mm

# SILFILL CONDUCTIVE ADHESIVE

## AS Shielding

### Further Specifications:

---

SILVER COPPER LOADED RTV SILICONE: PPT Bond AS-H

#### UNCURED PROPERTIES

Colour	Tan
Form	Semi flowable paste
Cure time at 23oC / 50% RH	24 Hours
Recommended minimum time before stressing bond	48 Hours

#### CURED PROPERTIES

Density	3.3g/cm3
Hardness	65 Shore A
Adhesion – lap shear (aluminium to aluminium)	150 N.cm2
Compression recommended (allowed range) 25%	(10 - 50%)
Service temperature range	-50oC to 125oC
Bond resistance (aluminium to aluminium)	<10mΩ/cm2
Thermal conductivity	1.0 Wm/K
Recommended bond thickness	0.05 - 05mm